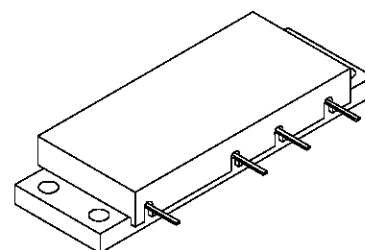


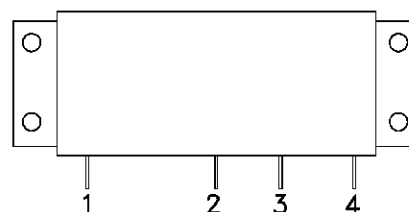
## RF POWER MODULES

### SATELLITE COMMUNICATIONS APPLICATIONS

PRELIMINARY DATA

- SATELLITE COMMUNICATIONS AMPLIFIER
- 1625 - 1665 MHz
- 18/28 VOLTS
- INPUT/OUTPUT 50 OHMS
- $P_{OUT} = 10\text{ W MIN.}$
- $GAIN = 30\text{ dB MIN.}$

**CASE STYLE H150**
**ORDER CODE**  
 STM1645-10

**BRANDING**  
 STM1645-10
**PIN CONNECTION**

- |                   |                   |
|-------------------|-------------------|
| 1. RF Input       | 2. $V_{C1}$ , 18V |
| 3. $V_{C2}$ , 28V | 4. RF Output      |

**DESCRIPTION**

The STM1645-10 module is designed for high power satellite communication applications in the 1.6 GHz frequency range operating at 28 Volts.

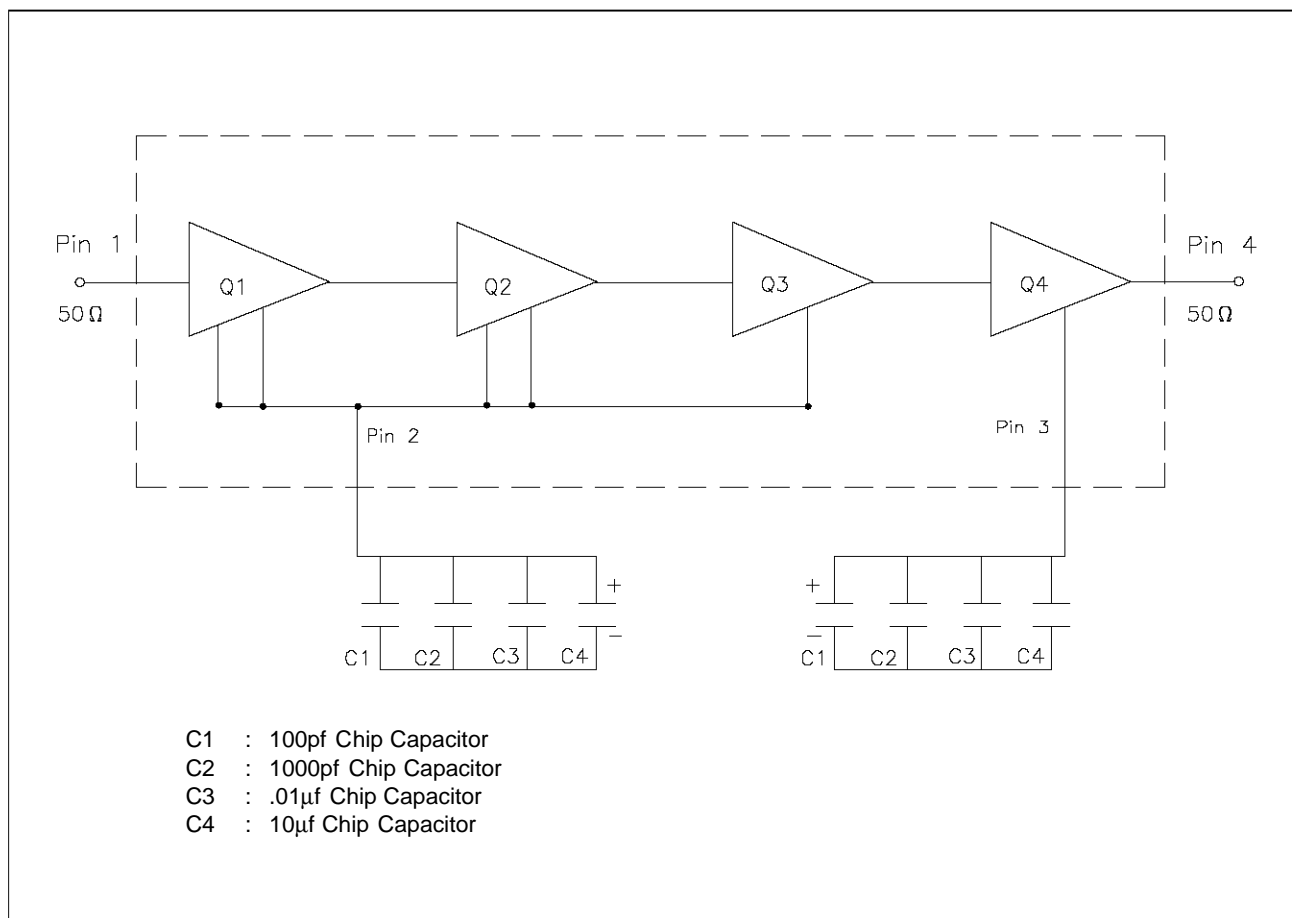
**ABSOLUTE MAXIMUM RATINGS ( $T_{case} = 25^{\circ}\text{C}$ )**

Symbol	Parameter	Value	Unit
$V_{C1}$	DC Supply Voltage	20	Vdc
$V_{C2}$	DC Supply Voltage	32	Vdc
$P_{IN}$	RF Input Power	20	mW
$P_{OUT}$	RF Output Power	16	W
$T_{STG}$	Storage Temperature	- 40 to +100	$^{\circ}\text{C}$
$T_C$	Operating Case Temperature	- 35 to +70	$^{\circ}\text{C}$

**ELECTRICAL SPECIFICATIONS ( $T_{\text{case}} = 25\text{ }^{\circ}\text{C}$ ,  $V_{C1*} = 18\text{ V}$ ,  $V_{C2} = 28\text{ V}$ )**

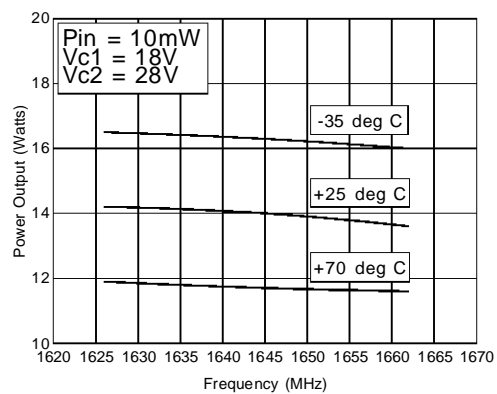
Symbol	Parameter	Test Conditions	Value			Unit
			Min.	Typ.	Max.	
BW	Frequency Range		1625	—	1665	MHz
$P_{\text{IN}}$	Input Power	$P_{\text{OUT}} = 10\text{ W}$	—	—	10.0	dBm
$G_P$	Power Gain	$P_{\text{OUT}} = 10\text{ W}$	30	—	—	dB
$\eta$	Efficiency	$P_{\text{OUT}} = 10\text{ W}$	30	35	—	%
H	Harmonics	$P_{\text{OUT}} = 10\text{ W}$ reference	—	-45	-40	dBc
$Z_{\text{IN}}$	Input Impedance	$P_{\text{OUT}} = 10\text{ W}$ $Z_G, Z_L = 50\Omega$	—	1.5:1	2.0:1	VSWR
—	Load Mismatch	VSWR = 10:1 $V = 28\text{ Vdc}$ $P_{\text{OUT}} = 10\text{ W}$	No Degradation in Output Power			

\*Note:  $V_{C1} = 18\text{ V}$  Regulated  $\pm 1\%$

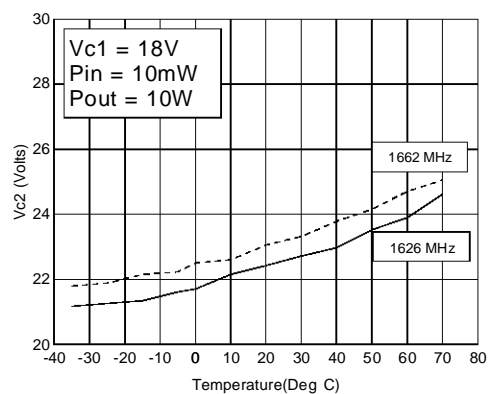
**D.C. TEST FIXTURE BYPASSING**

## TYPICAL PERFORMANCE

POWER OUTPUT vs FREQUENCY



VC2 vs FLANGE TEMPERATURE



## **APPLICATIONS RECOMMENDATIONS**

### **OPERATION LIMITS**

The STM1645-10 power module should never be operated under any condition which exceeds the Absolute Maximum Ratings presented on this data sheet. Nor should the module be operated continuously at any of the specified maximum ratings. If the module is to be subjected to one or more of the maximum rating conditions, care must be taken to monitor other parameters which may be affected.

### **DECOUPLING**

Failure to properly decouple any of the voltage supply pins may result in oscillations at certain operating frequencies. Therefore, it is recommended that these pins be bypassed as indicated in the Module DC and Test Fixture Configuration drawing of this data sheet.

### **POWER CONTROL**

The recommended method of power control for the STM1645-10 is to set  $P_{IN} = 10\text{mW}$ ,  $V_{C1} = 18\text{V}$  and  $V_{C2} = 28$  volts nominal at a flange temperature of  $25^{\circ}\text{C}$  to achieve an output power of 10 watts. Varying  $V_{C2}$  will allow stable power control over a wide range of flange temperature. The current consumption of  $V_{C2}$  is typically 850mA to 900mA for 10 watts power output.

### **MODULE MOUNTING**

To insure adequate thermal transfer from the module to the heatsink, it is recommended that a satisfactory thermal compound such as Dow Corning 340, Wakefield 120-2 or equivalent be applied between the module flange and the heatsink.

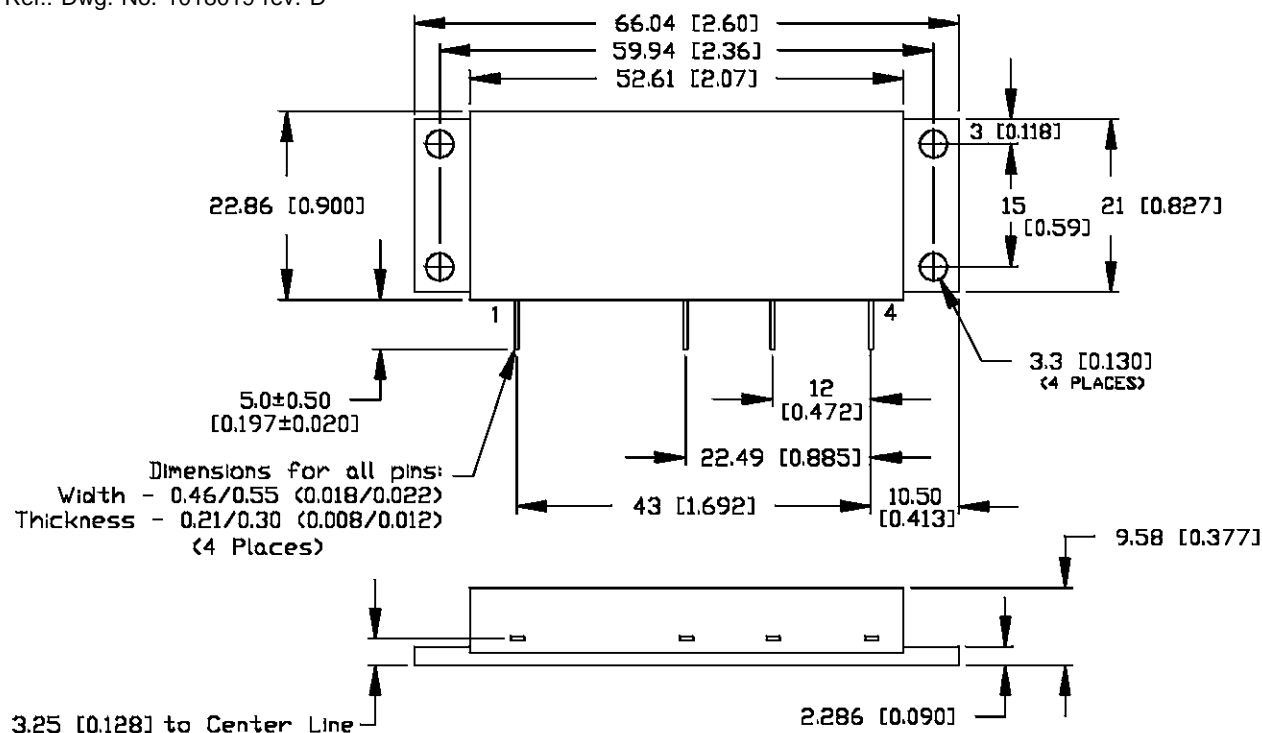
The heatsink mounting surface under the module should be flat to within  $\pm 0.05\text{mm}$  ( $\pm 0.002$  inch). The module should be mounted to the heatsink using 3 mm (or 4-40) or equivalent screws torqued to 5-6 kg-cm (4-6 in-lb).

The module leads should be attached to equipment PC board using  $180^{\circ}\text{C}$  solder applied to the leads with a properly grounded soldering iron tip, not to exceed  $195^{\circ}\text{C}$ , applied a minimum of 2mm (0.080 inch) from the body of the module for a duration not to exceed 15 seconds per lead. It is imperative that no other portion of the module, other than the leads, be subjected to temperatures in excess of  $100^{\circ}\text{C}$  (maximum storage temperature), for any period of time, as the plastic moulded cover, internal components and sealing adhesives may be adversely affected by such conditions.

Due to the construction techniques and materials used within the module, reflow soldering of the flange heatsink or leads, is not recommended.

## PACKAGE MECHANICAL DATA

Ref.: Dwg. No. 1018019 rev. D



## NOTES:

All tolerances  $\pm 0.25\text{mm}$  [ $\pm 0.010\text{in}$ ] unless otherwise specified.  
Numbers in [ ] are inches.

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